

Copyright FCI



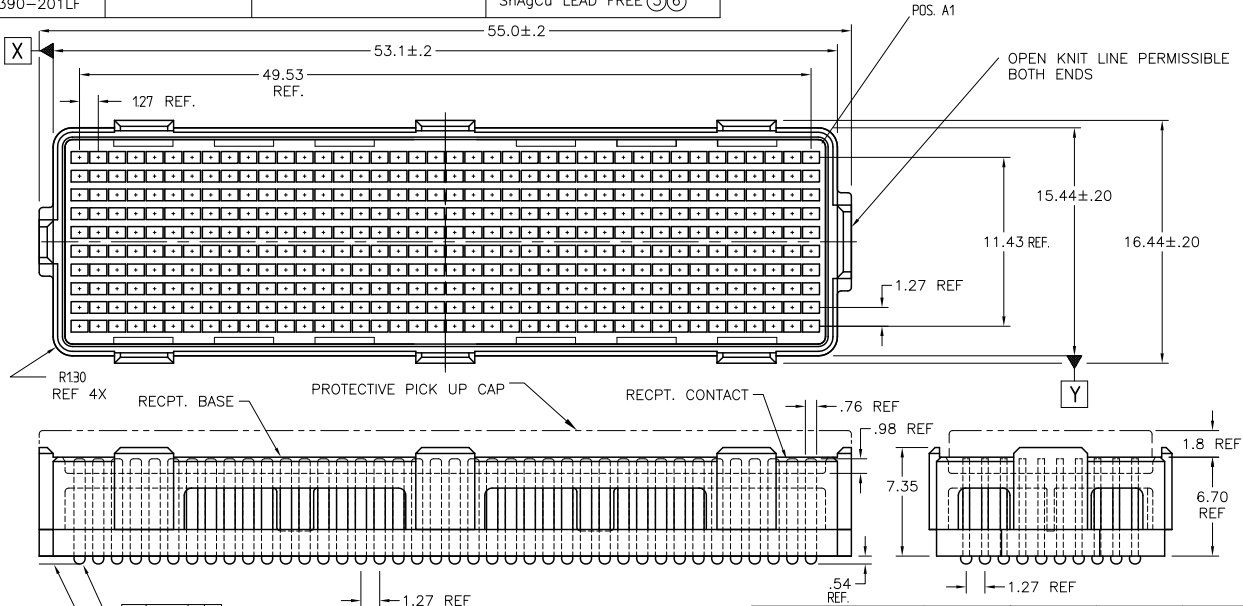
FCIconnect.com

1 | 2

3

4

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74390-001	YES	15u" (.38um) Au OVER Ni	SnPb
74390-001LF			SnAgCu LEAD FREE (5)(6)
74390-101	YES	30u" (.76um) Au OVER Ni	SnPb
74390-101LF			SnAgCu LEAD FREE (5)(6)
74390-201	YES	SEE NOTE 4.	SnPb
74390-201LF			SnAgCu LEAD FREE (5)(6)



mat'l. code	SEE NOTE 1	surface ASME Y14.5	tolerance ASME Y14.5	projection	product family
ltr	ec'n no	dr	date	tolerances unless otherwise specified	MEG-ARRAY
L	V06-0560	LP	2006-06-23	angles X=3	title
M	V09-0493	RE	2009-10-21	XXX=19	8mm RECPT. ASSY
				XXX=051	10 X 40= 400 POS.
G	V00196	HJ	2000-07-02	dr	D WAUGHEN
H	V20006	BRW	2002-01-03	engr	T LEMKE
J	V03-0679	DAI	2003-06-19	chr	T LEMKE
K	V04-0940	VS	2004-10-18	appd	T LEMKE
sheet	revision	M	M	M	
index	sheet	1	2	3	

form A4mmXlc

1

2

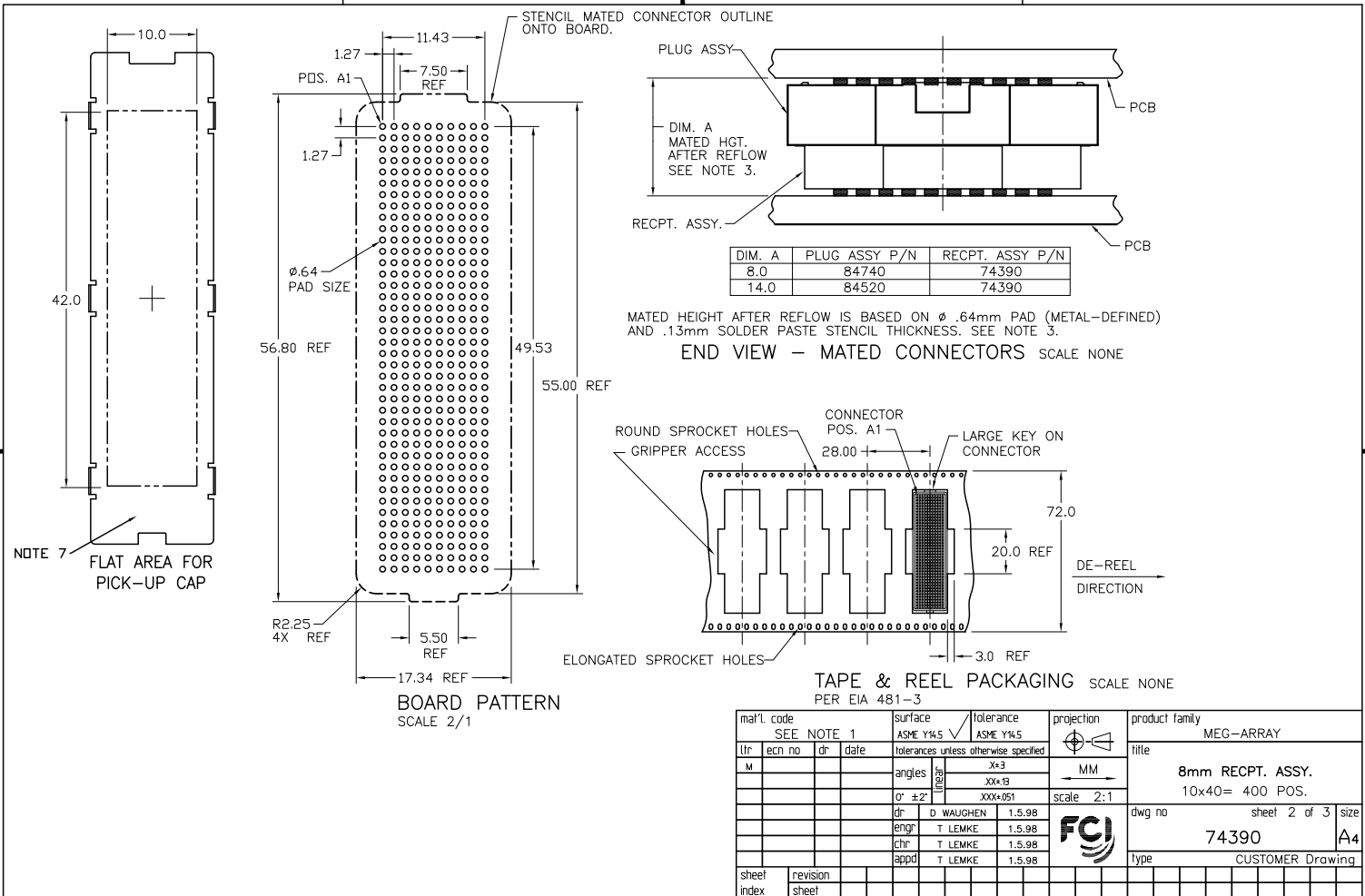
3

4

PDM: Rev:M

STATUS: Released

Printed: Oct 21, 2010



DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
8.0	84740	74390
14.0	84520	74390

MATED HEIGHT AFTER REFLOW IS BASED ON $\phi .64$ mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

TAPE & REEL PACKAGING SCALE NONE PER EIA 481-3

mat'l. code	SEE NOTE 1	surface	tolerance	projection	product family
lfr	ec'n no	ASME Y14.5	ASME Y14.5		MEG-ARRAY
	dr	tolerances unless otherwise specified		MM	title
M		angles	X=3	scale 2:1	8mm RECPT. ASSY. 10x40= 400 POS.
		0° ±2'	XX=19		dwg no
			XXX=051		74390
		dr	D WAUGHEN 1.5.98		sheet 2 of 3
		engr	T LEMKE 1.5.98		A4
		chr	T LEMKE 1.5.98		type
		appd	T LEMKE 1.5.98		CUSTOMER Drawing
sheet index	revision sheet				

NOTES:

- ①. **MAT'L:**
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING
CONTACT: (SEE TABLE ON SHEET1)
SOLDER BALL: (SEE TABLE ON SHEET1)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu
- ②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④. PLATING FOR -2XX SERIES DASH NOS: Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION
- ⑦. COMPANY LOGO TO APPEAR IN THIS AREA.

mat'l. code		SEE NOTE 1		surface	tolerance	projection	product family
lfr	ecm no	dr	date	ASME Y14.5 ✓	ASME Y14.5		MEG-ARRAY
M				tolerances unless otherwise specified	X=3	MM	title
				angles	XX+13	scale 2:1	8mm RECPT. ASSY. 10x40= 400 POS.
				0° ±2'	XXX+051		dwg no
				dr	D WAUGHEN 1.5.98		sheet 3 of 3
				engr	T LEMKE 1.5.98		74390
				chr	T LEMKE 1.5.98		A4
				appd	T LEMKE 1.5.98		type
sheet index	revision sheet						CUSTOMER Drawing